

Compact type with main unit height of 1.2mm that enables single-side recoil stroke 2mm



### Typical Specifications



Items		Specifications
Rating (max.)/(min.) (Resistive load)		10mA 5V DC / 50μA 3V DC
Contact resistance (Initial performance / After lifetime)		10Ω max. / 10Ω max.
Operating force		1±0.5N
Operating life	Without load	100,000 cycles
	With load	100,000 cycles (10mA 5V DC)

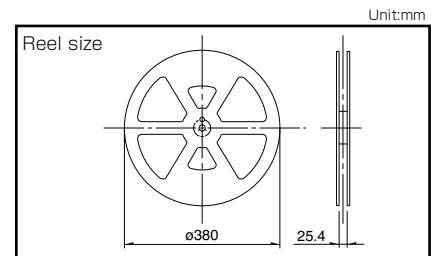
### Product Line

Travel (mm)	Operating section directions	Poles	Positions	Changeover timing	Soldering	Operating	Shape of flame leg	Location lug	Minimum order unit (pcs.)		Products No.	Drawing No.
									Japan	Export		
2	Horizontal	1	2	Not specified	Reflow	Left-side recoil	Flat	Without	6,000	24,000	<b>SSAL120100</b>	1
						Right-side recoil					<b>SSAL220100</b>	2
						Left-side recoil	For PC board insert		4,500	18,000	<b>SSAL120201</b>	3
						Right-side recoil					<b>SSAL220200</b>	4

### Packing Specifications

#### Taping

Product No.	Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
	1 reel	1 case / Japan	1 case / export packing		
<b>SSAL120100</b> <b>SSAL220100</b>	6,000	12,000	24,000	24	428×413×172
<b>SSAL120201</b> <b>SSAL220200</b>	4,500	9,000	18,000		



### Dimensions

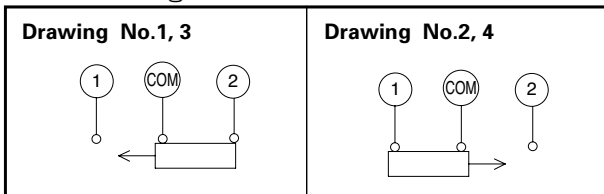
No.	Style	PC board mounting hole and land dimensions (Viewed from the direction A)
1		

■ Dimensions

Unit:mm

No.	Style	PC board mounting hole and land dimensions (Viewed from the direction A)
2		
3		
4		

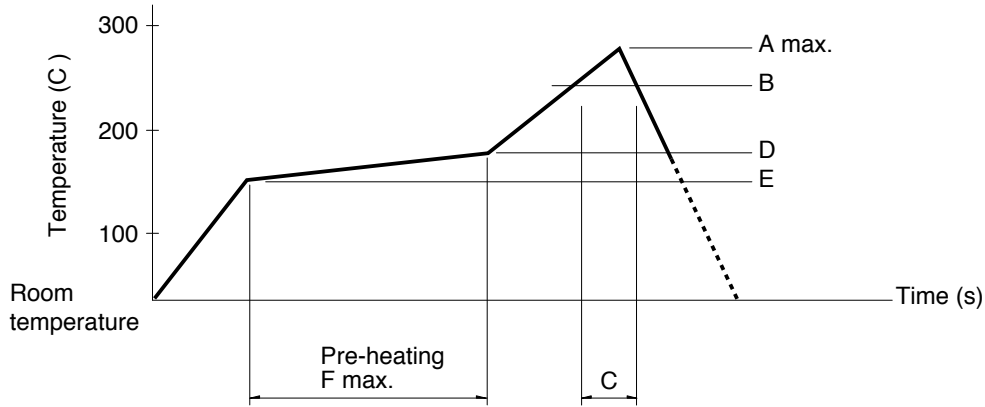
■ Circuit Diagram (Viewed from Direction A)





## Example of Reflow Soldering Condition

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple  $\phi$  0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface).  
A heat resisting tape should be used for fixed measurement.
3. Temperature profile



Series (Reflow type)		A (°C) 3s max.	B (°C)	C (s)	D (°C)	E (°C)	F (s)
SSSS2	Vertical 1-pole, 3-position	260	230	40	180	150	120
	Horizontal 1-pole, 2-position 1-pole, 3-position 2-pole, 3-position						
	Vertical 1-pole, 2-position	250					
SSSS7		260					
SSAH, SSAG, SSAJ, SSAL, SSSS8		260					

## Notes

1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

## Reference for Hand Soldering

Series	Soldering temperature	Soldering time
SSSF, SSSU	350±10°C	3+1/0s
SSSS2	350±10°C	4s max.
SSSS9	350±10°C	3s max.
SSAH, SSAG, SSAJ, SSAL	350±5°C	3s max.
SSSS8	330±5°C	3s max.
SSSS7	320±5°C	3s max.
SSAC	300±10°C	2s max.

## Reference for Dip Soldering

(For PC board terminal types)

Series	Items		Dip soldering	
	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion
SSSS2	100°C max.	60s max.	260±5°C	3±1s
SSSS9	120°C max.	60s max.	260±5°C	5+0/-1s (2 times)
SSSF, SSSU	100°C max.	60s max.	260±5°C	10±1s/5±1s
SSAC	100°C max.	60s max.	260±5°C	5±1s